

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	50	("5561293" "6103430" "6208751" "5985680" "6051845" "6097484" "6122562" "6185707" "6268717" "6291115" "6553329" "6674888" "5870187" "4849804" "5787190" "5841893" "6025206" "6185322" "3615466" "3615464" "3615463" "4495628" "4587480" "5665199" "5665609" "5869395" "5913103" "6174632" "6175938" "6264467" "6798526" "5847821" "6020957" "6091845" "6166801" "6171874" "6204917" "6205239" "6238940" "5254830" "5344793" "5450326" "5761064" "5780929" "5798192" "5843831" "5896294" "5961269" "5965306" "5965303").pn.	US-PGPUB; USPAT	OR	ON	2005/09/20 12:24
L3	3	L2 and ((scan with defect with location) same surface)	US-PGPUB; USPAT	OR	ON	2005/09/20 08:51
L9	14	process and tool and wafer and defect and surface and wafer and (process adj tool) and (wafer with surface) and (defect with location with scan\$)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/20 12:32
S1	1	10/658168	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/19 13:34
S2	4	knoch-john-\$.in. leek-deborah-\$.in. strader-nathan-\$.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 17:57
S3	3211	Isi adj logic adj corporation\$.as.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 17:57
S4	89	(S2 S3) and (process and tool and wafer and defect)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 17:59
S5	75	(S2 S3) and process and tool and wafer and defect and surface and wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 18:00

S7	4	(S2 S3) and process and tool and wafer and defect and surface and wafer and (process adj tool)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 18:01
S8	4	(S2 S3) and process and tool and wafer and defect and surface and wafer and (process adj tool) and (wafer with surface)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 18:01
S9	1	(S2 S3) and process and tool and wafer and defect and surface and wafer and (process adj tool) and (wafer with surface) and (defect with location)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 18:01
S10	89	process and tool and wafer and defect and surface and wafer and (process adj tool) and (wafer with surface) and (defect with location)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 18:02
S11	84	process and tool and wafer and defect and surface and wafer and (process adj tool) and (wafer with surface) and (defect with location) and scan\$	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 18:03
S13	4	process and tool and wafer and defect and surface and wafer and (process adj tool) and (wafer with surface) and (defect with location with scan\$) and (calculat\$ same defect same location same process same tool)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 18:04
S23	2	(us-20020161532-\$.did. "6701259". pn.) and (process with tool) and (defect same location same surface same wafer) and (process\$3 same wafer same tool) and ((calculat\$3 determin\$3) same defect same location) and detect\$3 and (add\$3 sum\$4 combine combined combining add sum)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/19 16:06
S25	54	(plot same number same defect same wafer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/19 13:35
S26	9	(plot same number same defect same wafer same semiconductor)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/19 15:14

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L3	3	L2 and ((scan with defect with location) same surface)	US-PGPUB; USPAT	OR	ON	2005/09/20 08:51
L9	14	process and tool and wafer and defect and surface and wafer and (process adj tool) and (wafer with surface) and (defect with location with scan\$)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/20 13:01
L10	310	702/81.CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/20 13:01
L11	127859	"430".CLAS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/20 13:02
L12	172143	"438".CLAS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/20 13:02
L13	5243	(L10 L11 L12) and (process\$3 with tool)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/20 13:02
L14	1632	(L10 L11 L12) and (process\$3 with tool) and defect	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/20 13:03

L15	1413	(L10 L11 L12) and (process\$3 with tool) and defect and wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/20 13:03
L16	730	(L10 L11 L12) and (process\$3 with tool) and defect and wafer and location	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/20 13:03
L18	538	(L10 L11 L12) and (process\$3 with tool) and defect and wafer and location and (detect\$3 scan scanning)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/20 13:04
L19	346	(L10 L11 L12) and (process\$3 with tool) and defect and wafer and location and (detect\$3 scan scanning) and (wafer with surface)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/20 13:04
L20	62	(L10 L11 L12) and (process\$3 with tool) and defect and wafer and location and (detect\$3 scan scanning) and (wafer with surface) and (defect with location)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/20 13:05
L21	25	(L10 L11 L12) and (process\$3 with tool) and defect and wafer and location and (detect\$3 scan scanning) and (wafer with surface) and (defect with location) and ((plot map) with defect)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/20 13:13
L22	7	(L10 L11 L12) and (process\$3 with tool) and defect and wafer and location and (detect\$3 scan scanning) and (wafer with surface) and (defect with location) and ((plot map) with defect) and ((added combined) with defect)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/20 13:14